



# 公司簡介

MOCVD 創造世界級之競爭力

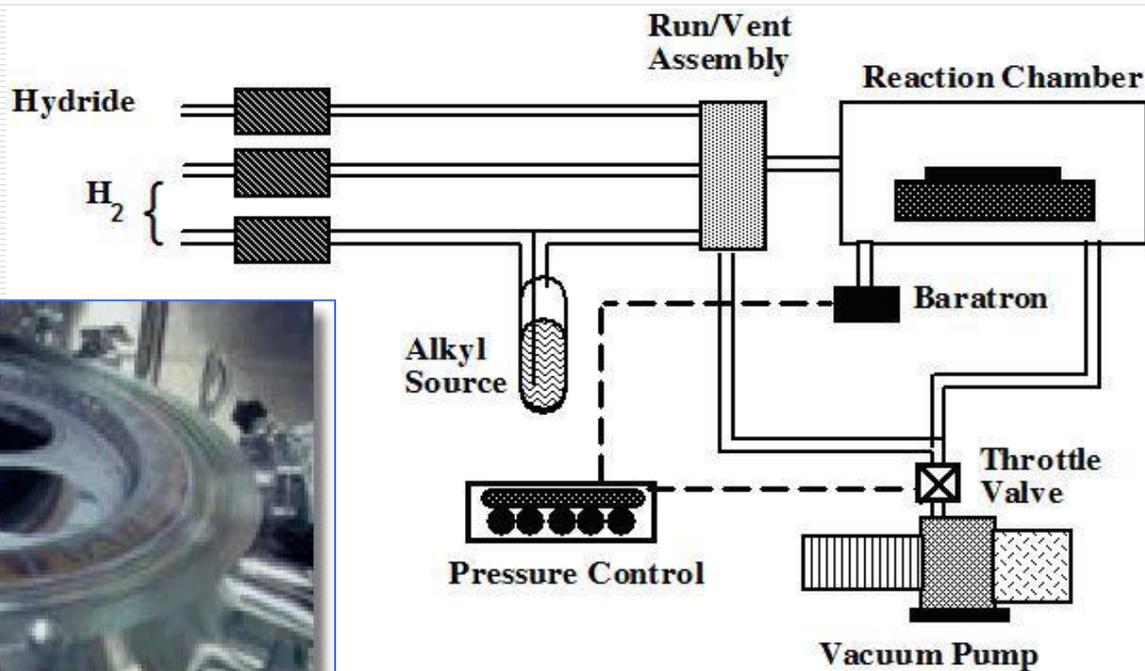




# 核心技術

## MOCVD (有機金屬氣相沉積法)

- Metal Organic Chemical Vapor Deposition





# 核心技術

生產  
機台

MOCVD有機金屬化學氣相沉積法  
Metal Organic Chemical Vapor Deposition

生產  
方式

透過有機金屬化學氣相沉積法，在基板上生長半導體薄膜的方式，同時透過機台即時監控，精確控制磊晶層，完成砷化鎵、磷化銦、氮化鎵等不同產品磊晶片生產。

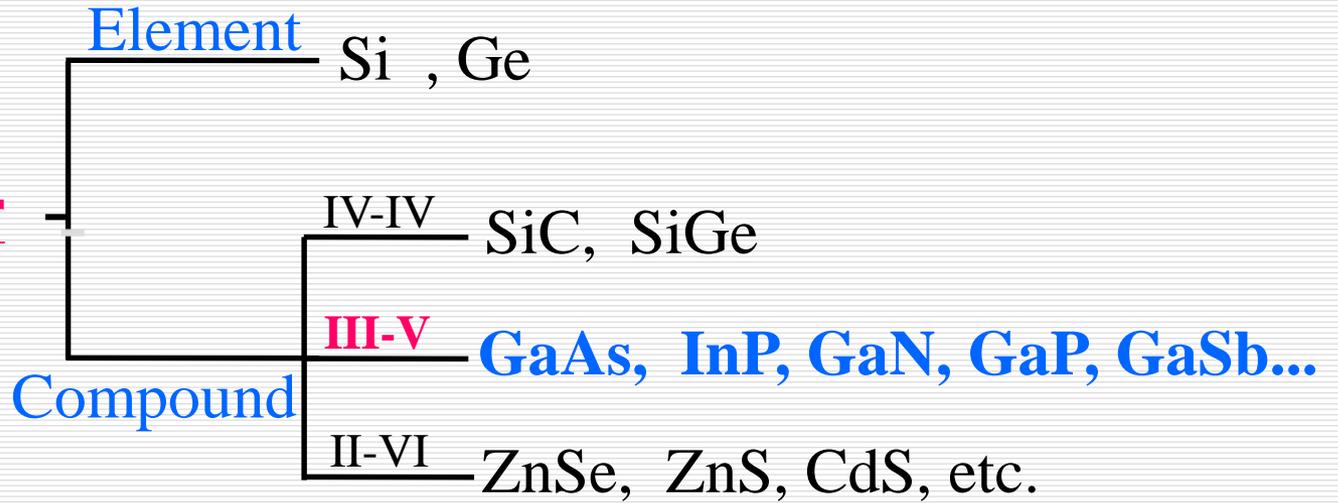
生產  
原理

磊晶層是由MOCVD在腔體中加熱基板，一個原子層，層層堆疊，行成磊晶層。



# 半導體分類 (依使用材料)

## Semiconductor

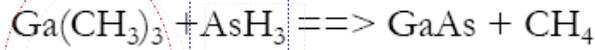


Period	Column II	III	IV	V	VI
2	Be 鈹 Beryllium	B 硼 Boron	C 碳 Carbon	N 氮 Nitrogen	O 氧 Oxygen
3	Mg 鎂 Magnesium	Al 鋁 Aluminum	Si 矽 Silicon	P 磷 Phosphorus	S 硫 Sulfur
4	Zn 鋅 Zinc	Ga 鎵 Gallium	Ge 鍺 Germanium	As 砷 Arsenic	Se 硒 Selenium
5	Cd 鎘 Cadmium	In 銦 Indium	Sn 錫 Tin	Sb 銻 Antimony	Te 碲 Tellurium
6	Hg 汞 Mercury	Tl 鉈 Thallium	Pb 鉛 Lead		

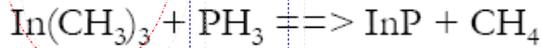
- 二元化合物 Binary : GaAs, InP, GaP, GaN, etc.
- 三元化合物 Ternary : InGaAs, InGaP, AlGaAs, etc.
- 四元化合物 Quaternary : AlGaInP, InGaAsP, etc.
- 五元化合物 Pentanary : AlGaInAsN, etc.



# 磊晶過程中之化學反應



化學反應式：



主要原物料：

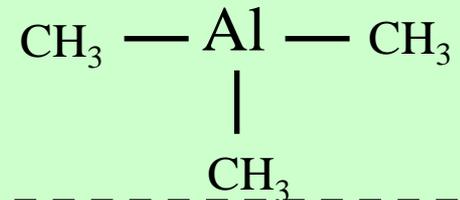
**MO Source** + **Hydride** + Carrier Gas : **H<sub>2</sub>**

TEAl : Tri-ethyl-Aluminum ( C<sub>2</sub>H<sub>5</sub> )<sub>3</sub>Al  
 TMGa : Tri-Methyl-Gallium ( CH<sub>3</sub> )<sub>3</sub> Ga  
 TMIn : Tri-Methyl-Indium ( CH<sub>3</sub> )<sub>3</sub>In  
 DETe : Di-ethyl-Tellurium ( C<sub>2</sub>H<sub>5</sub> )<sub>2</sub>Te  
 DEZn : Di-ethyl-Zinc ( C<sub>2</sub>H<sub>5</sub> )<sub>2</sub>Zn  
 CP<sub>2</sub>Mg : Bis (cyclo-penta-dienyl ) Magnesium 環戊二烯鎂

AsH<sub>3</sub> : Arsine  
 PH<sub>3</sub> : Phosphine  
 SiH<sub>4</sub> : Silane  
 Si<sub>2</sub>H<sub>6</sub> : Disilane  
 H<sub>2</sub>Se : Hydrogen Selenide  
 CBr<sub>4</sub> : Carbon Tetrabromide

TMAI    Tri - Methyl - Aluminum    ( CH<sub>3</sub> )<sub>3</sub>Al

三 甲 基                    鋁





# 化合物半導體材料特性

1. High Electron Mobility 高電子移動速率 (5.7x higher than CMOS)
2. High Frequency Response 高頻率響應
3. Wide Band Width 寬幅之頻寬
4. High Linearity 高線性度
5. High Power 高功率
6. Alternative Choice of Material 材料選擇多元性
7. 抗輻射

適用於微電子產品—HBT、pHEMT、BiHEMT、GaN on XX

光電子產品— PIN (PD、APD)、VCSEL、LD、SC、  
CW-Laser、 GaN on XX



# 微電子產品 產業供應鏈

Sumitomo, Freiburger, AXT

2~6 "GaAs Substrate

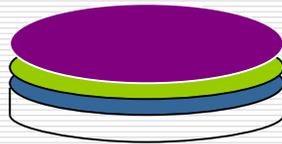


GaAs Epi- Wafer  
磊晶片



MOCVD Reactor

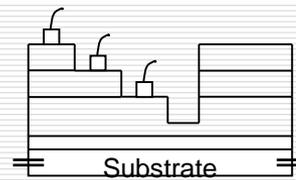
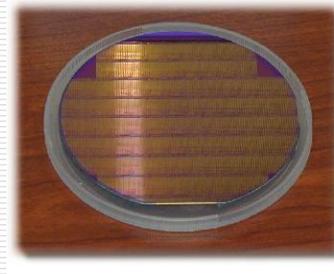
VPEC is a Pure  
Epi Provider



IDM : Qorvo, Skyworks

Fabless : Avago,  
Qualcomm, Richwave,

Microelectronics  
IC Process



Foundry :  
WIN, AWSC



Wireless  
Communication



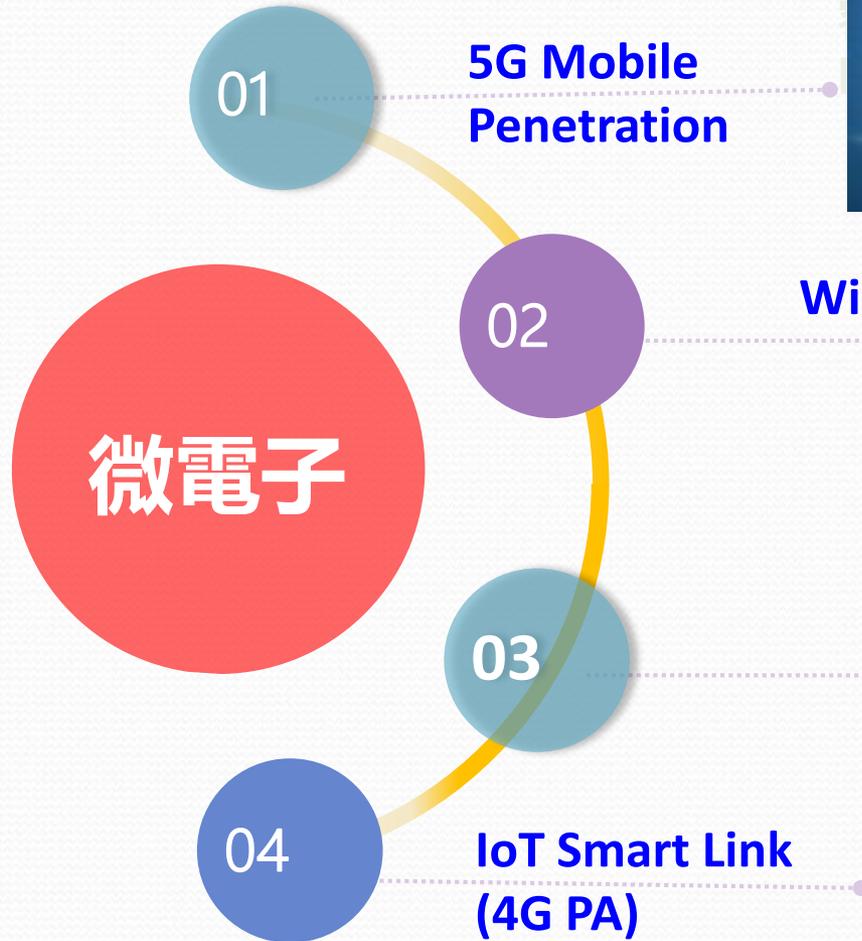
IC Package & Testing



# 2022年-2025年前三季度損益情形

	2025 Q1-Q3	%	2024	%	2023	%	2022	%
Revenue	2,420,554	100%	3,241,217	100%	2,694,104	100%	2,603,629	100%
Gross margin	862,133	36%	1,278,964	39%	1,108,914	41%	1,089,007	42%
Operating Profit	460,251	19%	721,214	22%	542,069	20%	579,950	22%
Non-operating income & expense	-38,854	-2%	96,460	3%	-347	0%	87,533	3%
Tax	-67,337	-3%	-146,619	-5%	-91,490	-3%	-122,755	-5%
Net income	354,060	15%	671,055	21%	450,232	17%	544,728	21%
EPS	1.92		3.63		2.43		2.95	

# 2025 Outlook



# 2025 Outlook



## 光電子

01

Data Center  
High Speed Connectivity



PD for 800G  
VCSEL for 400G & 800G

02

3D-sensing



VCSEL / PD

03

AR/VR



VCSEL

04

Future Driving Engines

無人機



AI glass

矽光子

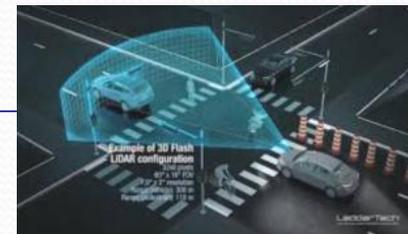
P-sensor、3D Sensing、ToF



低軌道衛星



車用光達(LD/PD)



# AI終端覺醒：感知×運算×機動

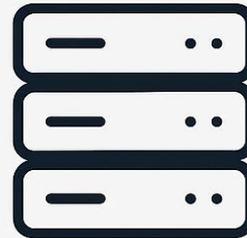


AI glass



Micro LED  
Wi-Fi 7  
ToF

AI datacenter



CW-laser  
VCSEL  
PD

Drone



Solar Cell  
Wi-Fi 7